

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,982,220 B1
APPLICATION NO. : 10/780605
DATED : January 3, 2006
INVENTOR(S) : Shiann-Ming Liou

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

ON THE TITLE PAGE, ITEM (56)

Add the following references

--5,495,398 02/1996 Takiar et al.--

--6,348,400 02/2002 Schoenfeld--

--6,169,331 B1 1-2001 Manning et al.--

TITLE PAGE, ITEM (57), REPLACE ABSTRACT WITH THE FOLLOWING:

A method of distributing power in a semiconductor die comprises providing at least one pair of bond pads to the semiconductor die. An input/output bond pad is provided to an outer periphery of the semiconductor die. The input/output bond pad receives an input/output bond wire operable for electrically connecting to a lead finger of a package. The lead finger is arranged on the package outside of the outer periphery of the semiconductor die. A single corresponding bond wire is connected between each of the pair of bond pads: such that each bond pad of each of the pair of bond pads has only one bond wire end connected thereto. A first bond pad of the pair of bond pads is located in an internal portion of the semiconductor die. The input/output bond pad is electrically connected to a second bond pad of the pair of bond pads.

IN THE PATENT:

Column 1, Line 22:	Delete "-" after "to"
Column 1, Line 34:	Delete " , " after "between"
Column 2, Line 2:	Delete "-" after "traces"
Column 3, Line 3:	Delete "device" and insert -- die --
Column 3, Line 5:	Delete "device" and insert -- die --
Column 3, Line 7:	Delete "device" and insert -- die--
Column 3, Line 8:	Delete "and" and insert -- an --
Column 3, Line 10:	Delete "leader" and insert -- lead --
Column 3, Line 23:	Insert -- of -- after "pad"
Column 3, Line 34:	Delete "first" after "a"
Column 3, Line 41:	Delete "interconnect" and insert -- interconnects --

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Column 4, Claim 10, Line 6: Delete "leader" and insert -- lead --
Column 4, Claim 14, Line 30: Delete "pad" after "bond"
Column 4, Claim 15, Line 35: Delete "all" and insert -- ball --

Signed and Sealed this

Fifth Day of December, 2006

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, sweeping initial "J" and a distinct "D".

JON W. DUDAS
Director of the United States Patent and Trademark Office